

Multi-Cure® 9-20801 Light-Curable Thermal Interface Material

APPLICATIONS

- Mounting Heat Sinks
- Bonding Heat Sensitive Components to PCBs

FEATURES

- UV Light Cure
- Secondary Activator or Heat Cure
- Highly Conductive
- Thixotropic for Easy Dispense and Placement Prior to Cure

OTHER FEATURES

- Superior Adhesion to FR4 and Many Metals
- Fast UV Cure for Immediate Fixture Strength

Dymax Multi-Cure® 9-20801 cures upon exposure to UV light, heat, and/or activator and is designed for rapid mounting of heat-sensitive components on printed circuit boards. Dymax 9-20801 is a Multi-Cure® material specially formulated to cure with heat or activator between opaque substrates. Most high-speed processes call for dispensing 9-20801 onto the substrate surface and then applying a thin layer of Dymax 501-E activator to the opposite component surface. The parts are mated and then exposed to light. This exposure cures the edges of the component in seconds so the parts are fixtured allowing for immediate handling and movement to the next step in the process. Material between the opaque surfaces will cure over time, typically minutes or hours. Dymax Multi-Cure® materials contain no nonreactive solvents and cure upon exposure to light. Their ability to cure in seconds enables faster processing, greater output, and lower processing costs. When cured with Dymax light-curing spot lamps, focused-beam lamps, or flood lamps, they deliver optimum speed and performance for bonding. Dymax lamps offer the ideal balance of UV and visible light for the fastest, deepest cures. This product is in full compliance with the RoHS Directives 2002/95/EC and 2003/11/EC.

UNCURED PROPERTIES *

Property	Value	Test Method
Solvent Content	No Nonreactive Solvents	N/A
Chemical Class	Acrylated Urethane	N/A
Appearance	Off White	N/A
Soluble in	Organic Solvents	N/A
Density, g/ml	2.0	ASTM D1875
Viscosity, cP (20 rpm)	110,000 (nominal)	ASTM D2556

ADHESION

Substrate	Recommendation
Lead Frame	✓
Ceramic	✓
PCB	✓
Flex	o
Silicon	✓

✓ Recommended o Limited Applications
st Requires Surface Treatment (e.g. plasma, corona treatment, etc.)

CURED MECHANICAL PROPERTIES *

Property	Value	Test Method
Durometer Hardness	D85	ASTM D2240
Tensile at Break, MPa [psi]	14 [2,100]	ASTM D638
Elongation at Break, %	NA	ASTM D638
Modulus of Elasticity, MPa [psi]	760 [110,000]	ASTM D638

OTHER CURED PROPERTIES *

Property	Value	Test Method
Boiling Water Absorption, % (2 h)	1.6	ASTM D570
Water Absorption, % (25°C, 24 h)	0.6	ASTM D570
Linear Shrinkage, %	0.39	ASTM D2566
Thermal Conductivity, W/m*K	0.9	ASTM D5470

* Not Specifications
N/A Not Applicable



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CURING GUIDELINES

Fixture time is defined as the time to develop a shear strength of 0.1 N/mm² [10 psi] between glass slides. Actual cure time typically is 3 to 5 times fixture time.

Dymax Curing System (Intensity)	Fixture Time or Belt Speed ^A
2000-EC (50 mW/cm ²) ^B	7s
5000-EC (200 mW/cm ²) ^B	5s
BlueWave® 75 (5.0 W/cm ²) ^B	4s
BlueWave® 200 (10 W/cm ²) ^B	4s
UVCS Conveyor with one 5000-EC (200 mW/cm ²) ^C	2 m/min [6.5ft/min]
UVCS Conveyor with Fusion F300S (2.5 W/cm ²) ^C	5 m/min [15 ft/min]

A Curing through light-blocking substrates may require longer cure times if they obstruct wavelengths used for light curing (320-400 nm for UV light curing, 320-450 nm for UV/Visible light curing). These fixture times/belt speeds are typical for curing thin films through 100% light-transmitting substrates.

B Intensity was measured over the UVA range (320-395 nm) using a Dymax ACCU-CAL™ 50 Radiometer.

C At 53 mm [2.1 in] focal distance. Maximum speed of conveyor is 8.2 m/min [27 ft/min]. Intensity was measured over the UVA range (320-395 nm) using the Dymax ACCU-CAL™ 100 Radiometer.

Full cure is best determined empirically by curing at different times and intensities, and measuring the corresponding change in cured properties such as tackiness, adhesion, hardness, etc. Full cure is defined as the point at which more light exposure no longer improves cured properties. Higher intensities or longer cures (up to 5x) generally will not degrade Dymax light-curable materials.

SECONDARY HEAT CURE

Heat can be used as a secondary cure mechanism where the adhesive cannot be cured with light. Light curing must be done prior to heat cure. The following heat-cure schedule may be used:

Temperature	Time*
110°C [230°F]	60 minutes
120°C [250°F]	30 minutes
150°C [300°F]	15 minutes

*Note: Actual heat cure time may vary due to part configuration, volume of adhesive applied, and oven efficiency.

ACTIVATOR CURE

Shadowed areas can be cured with activator.

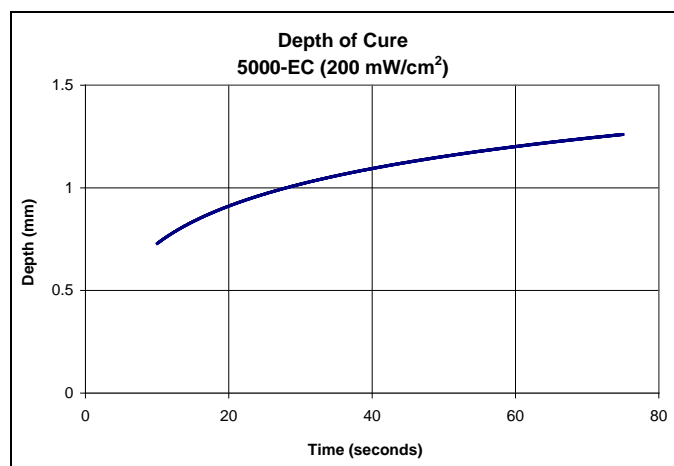
Activator is placed on one surface and the adhesive on the mating surface. Curing takes place at room temperature when the parts are mated. Activator requires closely mated parts (up to 0.5 mm [0.02 in] gap). Closely mated parts fixture (achieve handling strength) in less than a minute. See Dymax Technical Bulletin "Guidelines for Activator Curing" for complete instructions for all activators.

CURING GUIDELINES (CONTINUED)

Dymax recommends that customers employ a safety factor by curing longer, at higher intensity, and/or at higher temperature than required for full cure. Although Dymax Application Engineering can provide technical support and assist with process development, each customer ultimately must determine and qualify the appropriate curing parameters required for their unique application.

DEPTH OF CURE

The graphs below show the increase in depth of cure as a function of exposure time with two different lamps at different intensities. A 9.5 mm [0.37 in] diameter specimen was cured in a polypropylene mold and cooled to room temperature. It was then released from the mold and the cure depth was measured.



OPTIMIZING PERFORMANCE AND HANDLING

1. This product cures with exposure to UV light. Exposure to ambient and artificial light should be kept to a minimum before curing. Dispensing components including needles and fluid lines should be 100% light blocking, not just UV blocking.
2. All surfaces in contact with the material should be clean and free from flux residue, grease, mold release, or other contaminants prior to dispensing the material.
3. Cure speed is dependent upon many variables, including lamp intensity, distance from the light source, required depth of cure, thickness, and percent light transmission of components between the material and light source.
4. Oxygen in the atmosphere may inhibit surface cure. Surfaces exposed to air may require high-intensity ($>100 \text{ mW/cm}^2$) UV light to produce a dry surface cure. Flooding the curing area with an inert gas, such as nitrogen, can also reduce the effects of oxygen inhibition.
5. Parts should be allowed to cool after cure before testing and subjecting to any loads or electrical testing.
6. In rare cases, stress cracking may occur in assembled parts. Three options may be explored to eliminate this problem. One option is to heat anneal the parts to remove molded-in stresses. A second option is to open any gap between mating parts to reduce stress caused by an interference fit. The third option is to minimize the amount of time the liquid material remains in contact with the substrate(s) prior to curing.
7. Light curing generally produces some heat. If necessary, cooling fans can be placed in the curing area to reduce the heating effect on components.
8. At the point of curing, an air exhaust system is recommended to dissipate any heat and vapors formed during the curing process.

DISPENSING THE MATERIAL

This material may be dispensed with a variety of manual and automatic applicators or other equipment as required. Questions relating to dispensing and curing systems for specific applications should be referred to Dymax Application Engineering.

CLEANUP

Uncured material may be removed from dispensing components and parts with organic solvents. Cured material will be impervious to many solvents and difficult to remove. Cleanup of cured material may require mechanical methods of removal.

PERFORMANCE AFTER TEMPERATURE EXPOSURE

Dymax light-curable materials typically have a lower thermal limit of -54°C [-65°F] and an upper limit of 150°C [300°F]. Many Dymax products can withstand temperatures outside of this range for short periods of time, including typical wave solder processes and reflow profiles. Please contact Dymax Application Engineering for assistance.

STORAGE AND SHELF LIFE

Store the material in a cool, dark place when not in use. Do not expose to light. This product may polymerize upon prolonged exposure to ambient and artificial light. Keep covered when not in use. This material has a six-months shelf life from date of manufacture, unless otherwise specified, when stored between 10°C [50°F] and 32°C [90°F] in the original, unopened container.

GENERAL INFORMATION

This product is intended for industrial use only. Keep out of the reach of children. Avoid breathing vapors. Avoid contact with skin, eyes, and clothing. Wear impervious gloves. Repeated or continuous skin contact with uncured material may cause irritation. Remove material from skin with soap and water. Never use organic solvents to remove material from skin and eyes. For more information on the safe handling of this material, please refer to the Material Safety Data Sheet before use.